



Features

- Typ. $R_{DS(on)} = 20 \text{ m}$
- Ultra Low Gate Charge (typ. $Q_{G(tot)} = 220 \text{ nC}$)
- Low Effective Output Capacitance (typ. $C_{oss} = 258 \text{ pF}$)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

Typical Applications

- Automotive On Board Charger
- Automotive DC-DC Converter for EV/HEV

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol Value		Unit
Drain-to-Source Voltage			V_{DSS}	1200	V
Gate-to-Source Voltage			V_{GS}	-15/+25	V
Recommended Operation Values of Gate-to-Source Voltage		T _C < 175°C	V_{GSop}	-5/+20	V
Continuous Drain Current (Note 2)	Steady State	T _C = 25°C	I _D	98	Α
Power Dissipation (Note 2)			P _{DI}		

	DSC	807	Α
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)	IS	46	A

THERMAL RESISTANCE MAXIMUM RATINGS

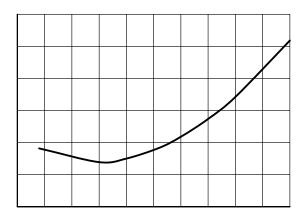
Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 2)	R _{JC}	0.32	°C/W
Junction-to-Ambient - Steady State (Notes 1, 2)	R _{JA}	41	

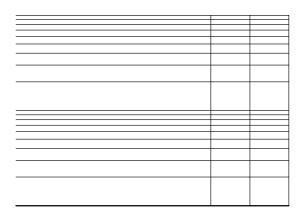
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA		1200			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 1 mA, referenced to 25°C			0.5		V/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 1200 V	T _J = 25°C			100	Α
			T _J = 175°C			1	mA
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +25/-15 V, V _{DS} = 0 V				±1	Α
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 20 \text{ mA}$		1.8	2.7	4.3	V
Recommended Gate Voltage	V_{GOP}			-5		+20	V
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 20 \text{ V}, I_D = 60 \text{ A}$	A, T _J = 25°C		20	28	m ę ,
		$V_{GS} = 20 \text{ V}, I_D = 60 \text{ A}$	A, T _J = 175°C		35	50	1

Forward Transconduc78 TmbF3 1 Tf.8295.28 466.413 .2948 .90707 r6.523 479.849 32.882 .90707 refD-.0033 Tc(to)Tj/TT3 14578 Tm0 Tc0 Tw(V)Tj 605.4

TYPICAL CHARACTERISTICS





TYPICAL CHARACTERISTICS (continued)

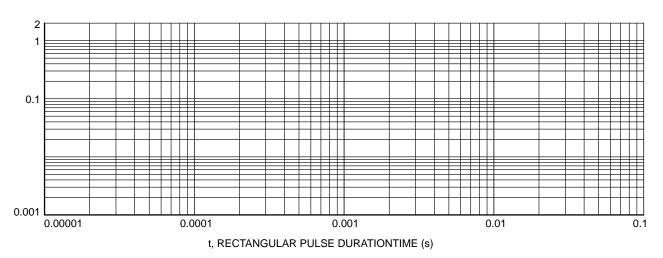


Figure 13. Junction-to-Case Transient Thermal Response Curve

D²PAK7 (TO-263-7L HV) CASE 418BJ ISSUE B

DATE 16 AUG 2019

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C

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

